

IEC QUALITY ASSESSMENT SYSTEM (IECQ)

covering Electronic Components,
Assemblies, Related Materials and Processes

For rules and details of the IECQ visit www.iecq.org

Schedule of Scope to Certificate of Approval

Independent Testing Laboratory

IECQ Certificate No.: IECQ-L ULTW 21.0003-03

CB Certificate No.: 50600528 ITL

Schedule Number: IECQ-L ULTW 21.0003-03-S Rev No.: 2 Revision Date: 2024/05/28 Page 1 of 2

Appendix-1 (50600528 ITL) Schedule of Scope to Certificate of Approval

Test Technology 測試項目	Test Method 測試標準		
Temperature, Bias, And Operating Life 温度偏压寿命试验	JEDEC JESD22-A108; AEC Q100-005。 SHJF-WI-RA-004		
Steady-State Temperature-Humidity Bias Life Test (THB) 恒定温湿度偏压寿命	JEDEC JESD22-A101 SHJF-WI-RA-007		
Highly Accelerated Temperature and Humidity Stress Test (HAST) 高加速温湿度应力试验	JEDEC JESD22-A110 SHJF-WI-RA-001		
High Temperature Storage Life (HTSL) 高温存储寿命试验	JEDEC JESD22-A103 SHJF-WI-RA-008		
Temperature Cycling (TC) 温度循环试验	JEDEC JESD22-A104 SHJF-WI-RA-009		
Accelerated Moisture Resistance - Unbiased Autoclave (PCT) 高压蒸煮试验	JEDEC JESD22-A102 SHJF-WI-RA-002		
Low Temperature Storage Life (LTSL) 低温存储寿命试验	JEDEC JESD22-A119 SHJF-WI-RA-010		
Power and Temperature Cycling (PTC) 功率和温度循环	JEDEC JESD22-A105 SHJF-WI-RA-013		
Early Life Failure Rate (ELFR) 早天测试	AEC Q100-008; JEDEC JESD22-A108。 SHJF-WI-RA-012		

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Preconditioning of Nonhermetic Surface Mount Devices Prior to Reliability Testing (Pre-con) 非密封表面贴装器件可靠性测试前的预处理	JEDEC JESD22-A113; JEDEC J-STD-020。 SHJF-WI-RA-011
Accelerated Moisture Resistance-Unbiased HAST (UHAST) 无偏压高加速试验	JEDEC JESD22-A118 SHJF-WI-RA-003
Resistance to Solder Shock for Through-Hole Mounted Devices 通孔安装器件的耐焊接性	JESD22-B106 SHJF-WI-RA-015
Solderability Tests for Component Leads, Terminations, Lugs, Terminals And Wires 元件引线、端子、挂耳、电线可焊性测试	J-STD-002 SHJF-WI-RA-014

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Technical Reviewer of DQS:		0	Date: 05/28/2024

